

# Di Xu

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/10723275/publications.pdf>

Version: 2024-02-01

7  
papers

273  
citations

1684188

5  
h-index

1720034

7  
g-index

9  
all docs

9  
docs citations

9  
times ranked

238  
citing authors

#	ARTICLE	IF	CITATIONS
1	Modulation of Crystallographic Texture and Twinning Structure of Cu Nanowires by Electrodeposition. Journal of the Electrochemical Society, 2013, 160, D207-D211.	2.9	24
2	Electromigration failure with thermal gradient effect in SnAgCu solder joints with various UBM. , 2009, , .		10
3	Nanotwin-modified copper interconnects and its effect on the physical properties of copper. , 2009, , .		0
4	<i>In situ</i> measurements of stress evolution for nanotwin formation during pulse electrodeposition of copper. Journal of Applied Physics, 2009, 105, .	2.5	71
5	Nanotwin formation and its physical properties and effect on reliability of copper interconnects. Microelectronic Engineering, 2008, 85, 2155-2158.	2.4	27
6	Structure and migration of (112) step on (111) twin boundaries in nanocrystalline copper. Journal of Applied Physics, 2008, 104, .	2.5	57
7	Nanotwin formation in copper thin films by stress/strain relaxation in pulse electrodeposition. Applied Physics Letters, 2007, 91, .	3.3	80